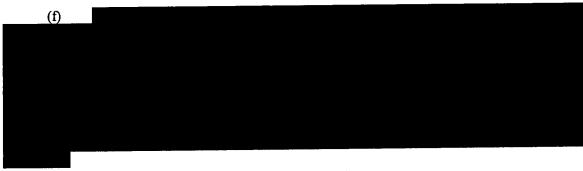
				PTO/SB/96 (11-08) red for use through 12/31/2008. OMB 0651-0031						
U.S. Patent and Trademark Office; U.S. DEPARTMENT OF COMMERCE Under the Paperwork Reduction Act of 1995, no persons are required to respond to a collection of information unless it displays a valid OMB control number.  STATEMENT UNDER 37 CFR 3.73(b)										
Applicant/Patent Owner: Aptina Imaging Corporation										
Application No./Patent No.:		7,154,136	Filed/Issue Date:	December 26, 2006						
ISOLATION STRUCTURES FOR PREVENTING PHOTONS AND CARRIERS FROM REACHING Entitled: ACTIVE AREAS AND METHODS OF FORMATION										
(Name of	Aptina Imaging (	orporation , a	Corpe Type of Assignee, e.g., corporation, partr	oration nership, university, government agency, etc.)						
states that	states that it is:									
1. X	the assignee of the	entire right, title, and intere	est; or							
2.	an assignee of less	than the entire right, title a	and interest.							
	(The extent (by per	centage) of its ownership in	nterest is %)							
in the pater	nt application/paten	t identified above by virtue	of either:							
re	A. An assignment from the inventor(s) of the patent application/patent identified above. The assignment was recorded in the United States Patent and Trademark Office at Reel									
OR	rame	, or for which a copy t	nereof is attached.							
B. X A chain of title from the inventor(s), of the patent application/patent identified above, to the current assignee as follows:  1. From: Bryan G. Cole et al. To: Micron Technology, Inc.  The document was recorded in the United States Patent and Trademark Office at  Reel 015010 , Frame 0537 , or for which a copy thereof is attached.										
2.	From: Micron	Technology, Inc.	To: Aptina Imagi	ing Corporation						
			ed States Patent and Traden							
	Reel	, Frame	, or for which a copy	thereof is attached.						
3.	From:		To:	<del></del>						
			ed States Patent and Traden							
<del> </del>	Reel	, Frame	, or for which a copy	thereof is attached.						
	Additional docui	ments in the chain of title a	are listed on a supplemental	sheet.						
As required by 37 CFR 3.73(b)(1)(i), the documentary evidence of the chain of title from the original owner to the assignee was, or concurrently is being, submitted for recordation pursuant to 37 CFR 3.11.										
[NOTE: A separate copy ( <i>i.e.</i> , a true copy of the original assignment document(s)) must be submitted to Assignment Division in accordance with 37 CFR Part 3, to record the assignment in the records of the USPTO. <u>See</u> MPEP 302.08]										
The undersigned (whose title is supplied below) is authorized to act on behalf of the assignee.										
	\$	Ta >		December 16, 2008						
<del></del>		Signature		Date						
		nas J. D'Amico		(202) 420-2232						
		d or Typed Name		Telephone Number						
4	Attorr	ey for Assignee Title								

#### PATENT ASSIGNMENT AGREEMENT

#### 1. Definitions

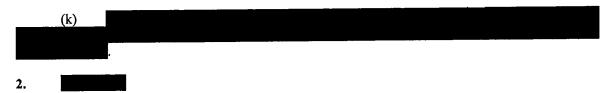
- (a) "Agreement" shall mean this Patent Assignment Agreement.
- (b) "Assignee" shall mean Aptina Imaging Corporation, a Cayman Islands corporation with offices at c/o Citco Trustees (Cayman) Limited, Regatta Office Park, West Bay Road, Grand Cayman, Y1-1205, Cayman Islands.
- (c) "Assignor" shall mean Micron Technology, Inc., a Delaware corporation with offices at 8000 South Federal Way, Boise, ID 83707.
  - (d) "Effective Date" shall mean October 3, 2008.





- (g) "Imaging Patents" shall mean those patents identified in ATTACHMENT "A" hereto, including, without limitation, all divisions, continuations, continuations-in-part, reissues, reexaminations, and all foreign counterparts thereof, and which may issue thereon or in connection therewith after the Effective Date of this Agreement.
- (h) "Imaging Patent Applications" shall mean those filed patent applications identified in ATTACHMENT "B" hereto, including, without limitation, all patents, divisions, continuations, continuations-in-part, reissues, reexaminations, and all foreign counterparts which may issue thereon or in connection therewith after the Effective Date of this Agreement.
- (i) "Semiconductor Patents" shall mean those patents identified in ATTACHMENT "D" hereto, including, without limitation, all divisions, continuations, continuations-in-part, reissues, reexaminations, and all foreign counterparts thereof, and which may issue thereon or in connection therewith after the Effective Date of this Agreement.

(j) "Semiconductor Patent Applications" shall mean those filed patent applications identified in ATTACHMENT "E" hereto, including, without limitation, all patents, divisions, continuations, continuations-in-part, reissues, reexaminations, and all foreign counterparts which may issue thereon or in connection therewith after the Effective Date of this Agreement.

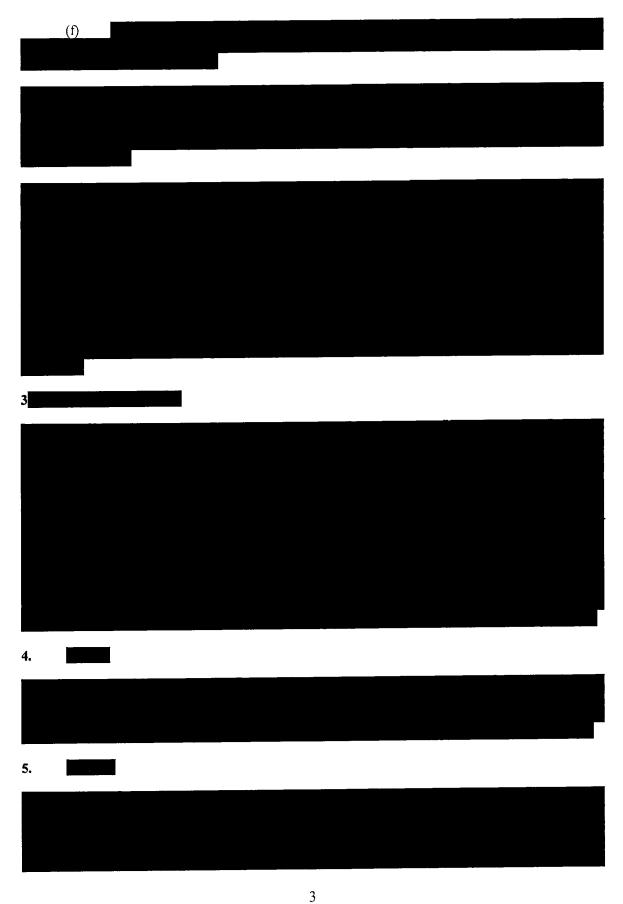


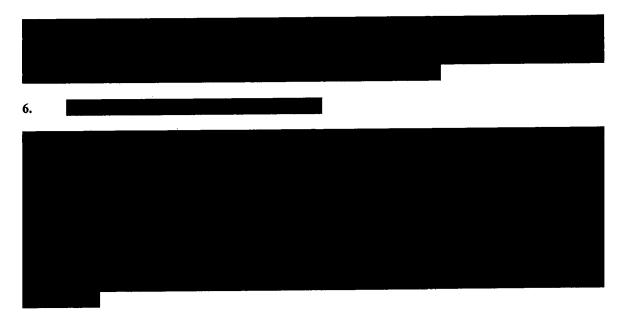
- (a) Subject to the terms and conditions of this Agreement, and subject to the rights of others existing as of the Effective Date of this Agreement if any, Assignor, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, hereby sells, assigns, and transfers to Assignee its entire right, title and interest in and to the Imaging Patents, including all rights to causes of action and remedies related thereto (including the right to sue for past, present or future infringement of rights related to the foregoing and the right to collect damages therefor). Assignor hereby authorizes and requests the Commissioner of Patents of the United States, and any other official of the United States and any country foreign to the United States whose duty it is to issue or record patents, to issue the Imaging Patents to Assignee.
- (b) Subject to the terms and conditions of this Agreement, and subject to the rights of others existing as of the Effective Date of this Agreement if any, Assignor, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, hereby sells, assigns, and transfers to Assignee its entire right, title and interest in and to the Intellectual Property rights in the Imaging Patent Applications. Assignor hereby authorizes and requests the Commissioner of Patents of the United States, and any other official of the United States and any country foreign to the United States whose duty it is to issue or record patents, to record assignment of the Imaging Patent Applications to Assignee.



- (d) Subject to the terms and conditions of this Agreement, and subject to the rights of others existing as of the Effective Date of this Agreement if any, and subject further to the restrictions on the Semiconductor Patents set out below, Assignor, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, hereby sells, assigns, and transfers to Assignee its entire right, title and interest in and to the Semiconductor Patents, including all rights to causes of action and remedies related thereto (including the right to sue for past, present or future infringement of rights related to the foregoing and the right to collect damages therefor). Assignor hereby authorizes and requests the Commissioner of Patents of the United States, and any other official of the United States and any country foreign to the United States whose duty it is to issue or record patents, to issue the Semiconductor Patents to Assignee.
- (e) Subject to the terms and conditions of this Agreement, and subject to the rights of others existing as of the Effective Date of this Agreement if any,

  Assignor, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, hereby sells, assigns, and transfers to Assignee its entire right, title and interest in and to the Intellectual Property rights in the Semiconductor Patent Applications. Assignor hereby authorizes and requests the Commissioner of Patents of the United States, and any other official of the United States and any country foreign to the United States whose duty it is to issue or record patents, to record assignment of the Semiconductor Patent Applications to Assignee.





### 7. General

This Agreement shall be effective as of the Effective Date hereof and shall be binding on the respective heirs, assigns, representatives, and successors of Assignor and of Assignee.

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	Micron Technology, Inc.  Signed:   Date:   2/16/42 , 2008
	nowledged to me that he did so of his own free will and in his  Signed:  My commission expires:  8/12/1/
R. SAMMAN OTAA	Agreed to by:  Aptina Imaging Corporation  Signed: Jour Jour Jour Jour Jour Jour Jour Jour
(uage)	nowledged to me that he did so of his own free will and in his  Signed:  My commission expires:

Agreed to by:

[Signature page to the Patent Assignment Agreement]

### ATTACHMENT "A"

## **IMAGING PATENTS**

# Aptina Issued

PATENT NUMBER	FILE NUMBER	TITLE	COUNTRY NAME	ISSUE DATE
7133076	PB(T-9066:00/US	CONTOURED SURFACE COVER PLATE: FOR IMAGE SENSOR ARRAY	United States of America	Nov 7, 2006
7133553	AVGO-0048.00/US	CORRELATION-BASED COLOR MOSAIC INTERPOLATION ADJUSTMENT USING LUMINANCE GRADIENTS	United States of America	Nov 7, 2005
7136157	2002-1174:00/US	METHOD AND APPARATUS FOR TESTING IMAGE SENSORS	United States of America	Nov 14, 2006
7141841	2003-0105.00/US	IMAGE SENSOR HAVING A TRANSISTOR FOR ALLOWING INCREASED DYNAMIC RANGE	United States of America	Nov 28, 2006
7142234	2002-1365.09/US	METHOD FOR MISMATCH DETECTION BETWEEN THE FREQUENCY OF LLUMINATION SOURCE AND THE DURATION OF OPTICAL INTEGRATION TIME FOR MAGER WITH POLLING SHUTTER	United States of America	Nov28,2006
7145189	2004-0296.00/US	PHOTON AMPLIFICATION FOR IMAGE SENSORS	United States of America	Dec 5, 2006
7148462	2003-0714.01/U\$	PIXEL WITH DIFFERENTIAL READOUT.	United States of America	Dec 12, 2006
7148528	2003-0106.00/US	PINNED PHOTODIODE STRUCTUR AND METHOD OF FORMATION	E United States of America	Dec 12, 2006
7148833	2005-0485:00(US	SHARING OPERATIONAL AMPLIFIER BETWEEN TWO STAGES OF PIPELINED ADC AND/OR TWO CHANNELS OF SIGNAL PROCESSING CIRCUITRY	United States of America	Dec 12,2006
7151472	PBIT-0158.01/US	REFERENCE VOLTAGE STABILIZATION IN CMOS SENSOR	United States of America	Dec 19, 2006
7(51 <b>476</b>	; 2003-1192-00/US	MINIMIZED DIFFERENTIAL SAR TYPE COLUMN WIDE ADC FOR CMOS IMAGE SENSORS	United States of America	Dec.19, 2006
7153719	2004-0396.00/US	METHOD OF FABRICATING A STORAGE GATE PIXEL DESIGN	United States of America	Dec 26, 2006
7154078	2002-0336.01/US	DIFFERENTIAL COLUMN READOUT SCHEME FOR CMOS APS PIXELS	United States of America	Dec 26, 2006
7154136	2003-0343.00/US	ISOLATION STRUCTURES FOR PREVENTING PHOTONS AND CARRIERS FROM REACHING ACTIVE AREAS AND METHODS OF	United States of America	Dec 26, 2006

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